



IEC 62769-101-2

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# INTERNATIONAL STANDARD



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**Field device integration (FDI) –  
Part 101-2: Profiles – Foundation Fieldbus HSE**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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### FIELD DEVICE INTEGRATION (FDI) –

### Part 101-2: Profiles – Foundation Fieldbus HSE

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International Standard IEC 62769-101-2 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) support for Package developers to build EDDs targeted for today's EDD bases system under a single development tool.

The text of this International Standard is based on the following documents:

CDV	Report on voting
65E/621/CDV	65E/684/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI)*, can be found on the IEC website.

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 101-2: Profiles – Foundation Fieldbus HSE

#### 1 Scope

This part of IEC 62769 specifies the IEC 62769 profile for IEC 61784-1, CP 1/2 (FOUNDATION™ Fieldbus HSE)<sup>1</sup>.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus Profiles*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control and electronic device description language (EDDL)*

IEC 62541-6, *OPC unified architecture – Part 6: Mappings*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

~~NOTE—IEC 62769-2 is technically identical to FDI-2022.~~

IEC 62769-3, *Field Device Integration (FDI) – Part 3: FDI Server*

~~NOTE—IEC 62769-3 is technically identical to FDI-2023.~~

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

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IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

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IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

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IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

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IEC 62769-101-1, *Field Device Integration (FDI) – Part 101-1: Profiles – Foundation Fieldbus H1*



# INTERNATIONAL STANDARD

# NORME INTERNATIONALE

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**Field device integration (FDI) –  
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI) –  
Partie 101-2: Profils – Foundation Fieldbus HSE**



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## FIELD DEVICE INTEGRATION (FDI) –

### Part 101-2: Profiles – Foundation Fieldbus HSE

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### Part 101-2: Profiles – Foundation Fieldbus HSE

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## COMMISSION ÉLECTROTECHNIQUE INTERNATIONALE

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### INTÉGRATION DES APPAREILS DE TERRAIN (FDI) –

#### Partie 101-2: Profils – Foundation Fieldbus HSE

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La Norme internationale IEC 62769-101-2 a été établie par le sous-comité 65E: Les dispositifs et leur intégration dans les systèmes de l'entreprise, du comité d'études 65 de l'IEC: Mesure, commande et automation dans les processus industriels.

Cette deuxième édition annule et remplace la première édition parue en 2015. Cette édition constitue une révision technique.

Cette édition inclut les modifications techniques majeures suivantes par rapport à l'édition précédente:

- a) prise en charge d'extensions de protocoles génériques, pour une adoption plus rapide d'autres technologies;
- b) capacité offerte aux développeurs de Paquetages d'élaborer des EDD qui ciblent les systèmes de bases EDD actuels, en exploitant un seul outil de développement.

Le texte de cette Norme internationale est issu des documents suivants:

CDV	Rapport de vote
65E/621/CDV	65E/684/RVC

Le rapport de vote indiqué dans le tableau ci-dessus donne toute information sur le vote ayant abouti à l'approbation de cette Norme internationale.

Ce document a été rédigé selon les Directives ISO/IEC, Partie 2.

Une liste de toutes les parties de la série IEC 62769, publiées sous le titre général *Intégration des appareils de terrain (FDI)*, peut être consultée sur le site web de l'IEC.

Le comité a décidé que le contenu de ce document ne sera pas modifié avant la date de stabilité indiquée sur le site web de l'IEC sous "<http://webstore.iec.ch>" dans les données relatives au document recherché. A cette date, le document sera

- reconduit,
- supprimé,
- remplacé par une édition révisée, ou
- amendé.

## INTÉGRATION DES APPAREILS DE TERRAIN (FDI) –

### Partie 101-2: Profils – Foundation Fieldbus HSE

#### 1 Domaine d'application

La présente partie de l'IEC 62769 spécifie le profil de l'IEC 62769 pour le profil de communication CP 1/2 (FOUNDATION™ Fieldbus HSE)<sup>1</sup> défini dans l'IEC 61784-1.

#### 2 Références normatives

Les documents suivants cités dans le texte constituent, pour tout ou partie de leur contenu, des exigences du présent document. Pour les références datées, seule l'édition citée s'applique. Pour les références non datées, la dernière édition du document de référence s'applique (y compris les éventuels amendements).

IEC 61784-1, *Réseaux de communication industriels – Profils – Partie 1: Profils de bus de terrain*

IEC 61784-2, *Réseaux de communication industriels – Profils – Partie 2: Profils de bus de terrain supplémentaires pour les réseaux en temps réel fondés sur l'ISO/IEC/IEEE 8802-3*

IEC 61804 (toutes les parties), *Blocs fonctionnels (FB) pour les procédés industriels et langage de description électronique de produit (EDDL)*

IEC 62541-6, *Architecture unifiée OPC – Partie 6: Mappings*

IEC 62541-100:2015, *Architecture unifiée OPC – Partie 100: Interface d'appareils*

IEC 62769-2, *Intégration des appareils de terrain (FDI) – Partie 2: Client FDI*

IEC 62769-3, *Intégration des appareils de terrain (FDI) – Partie 3: Serveur FDI*

IEC 62769-4, *Intégration des appareils de terrain (FDI) – Partie 4: Paquetages FDI*

IEC 62769-5, *Intégration des appareils de terrain (FDI) – Partie 5: Modèle d'Information FDI*

IEC 62769-6, *Intégration des appareils de terrain (FDI) – Partie 6: Mapping de technologies FDI*

IEC 62769-7, *Intégration des appareils de terrain (FDI) – Partie 7: Appareils de communication FDI*

IEC 62769-101-1, *Intégration des appareils de terrain (FDI) – Partie 101-1: Profils – Foundation Fieldbus H1*

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